IN THE CLAIMS:

Please CANCEL claims 39-41, 44-46, 49-51 and 54-56 without prejudice to or disclaimer of the recited subject matter.

Please AMEND claims 37, 38, 42, 43, 47, 48, 52, 53 and 57-59, and ADD new claims 60-63, as follows. For the Examiner's convenience, all claims currently pending in this application have been reproduced below:

1-36. (Canceled)

37. (Currently Amended) An electrostatic sensing apparatus for sensing a surface position of a shot region in a substrate to which a pattern is transferred by an exposure apparatus, said electronic sensing apparatus[[,]] comprising:

a plurality of detection sections; and

a system which selects at least one detection section from ~~the~~ said plurality of detection sections, based on layout information of [[a]] the shot region ~~of an object surface~~ to be detected, and calculates [[a]] the surface position ~~of the region,~~ based upon an output of ~~the~~ said selected at least one detection section.

38. (Currently Amended) ~~A lithographic system,~~ An exposure apparatus for transferring a pattern to a shot region in a substrate, said apparatus comprising:

an electrostatic sensor, for sensing a surface position of the shot region, having a plurality of detection sections; and

a ~~controller~~ system which selects at least one detection section from ~~the~~ said plurality of detection sections, based on layout information of [[a]] the shot region ~~of a substrate surface~~ to be detected, and calculates [[a]] the surface position ~~of the region,~~ based upon an output of ~~the~~ said selected at least one detection section.

39-41.(Canceled)

42. (Currently Amended) A device manufacturing method comprising steps of:

~~exposing~~ transferring a pattern to a substrate using ~~a lithography system as recited~~ an exposure apparatus as defined in claim 38; and

developing the ~~exposed~~ substrate to which the pattern has been transferred.

43. (Currently Amended) ~~A lithographic system,~~ An exposure apparatus for transferring a pattern to a shot region in a substrate, said apparatus comprising:

a plurality of electrostatic sensors, for sensing a surface position of the shot region, each having a plurality of detection sections; and

a ~~controller~~ system which selects at least one detection section from ~~each of the~~ said plurality of detection sections of said plurality of electrostatic sensors, based on layout information of [[a]] the shot region ~~of a substrate surface~~ to be detected, and calculates [[a]] the

surface position ~~of the region,~~ based upon outputs of ~~the~~ said selected ~~detection sections of the~~ at least one detection section of said one of said plurality of electrostatic sensors.

44-46. (Canceled)

47. (Currently Amended) A device manufacturing method comprising steps of:

~~exposing~~ transferring a pattern to a substrate using ~~a lithographic system as recited~~ an exposure apparatus as defined in claim 43; and

developing the ~~exposed~~ substrate to which the pattern has been transferred.

48. (Currently Amended) A scanning exposure apparatus for ~~exposing a substrate to a pattern of a mask~~ transferring a pattern of a mask to a shot region in a substrate by scanning the mask and the substrate relative to a slit-shaped exposure beam, said ~~exposure~~ apparatus comprising:

an electrostatic sensor, for sensing a surface position of the shot region, having a plurality of detection sections arranged in a direction perpendicular to a scanning direction of the mask and the substrate; and

a ~~controller~~ system which selects at least one detection section from ~~the~~ said plurality of detection sections, based on layout information of [[a]] the shot region ~~of a surface of the substrate~~ to be detected, and calculates [[a]] the surface position ~~of the region~~ based upon an output of ~~the~~ said selected at least one detection section.

49-51. (Canceled)

52. (Currently Amended) A device manufacturing method comprising steps of:

~~exposing~~ transferring a pattern to a substrate using a scanning exposure apparatus as ~~recited~~ defined in claim 48; and

developing the ~~exposed~~ substrate to which the pattern has been tranferred.

53. (Currently Amended) A scanning exposure apparatus for ~~exposing a substrate to a pattern of a mask~~ transferring a pattern of a mask to a shot region in a substrate by scanning the mask and the substrate relative to a slit-shaped exposure beam, ~~the exposure~~ said apparatus comprising:

a plurality of electrostatic sensors, for sensing a surface position of the shot region, each having a plurality of detection sections arranged in a direction perpendicular to a scanning direction of the mask and the substrate; and

~~a controller which selects at least one detection section from each of the plurality of electrostatic sensors, based on information of a region of a surface of the substrate to be detected, and calculates a position of the region, based upon outputs of the selected detection sections of the plurality of electrostatic sensors~~ a system which selects at least one detection section from said plurality of detection sections of one of said plurality of electrostatic sensors based on layout information of the shot region to be detected, and calculates the surface position

based upon outputs of said selected at least one detection section of said one of said plurality of electrostatic sensors.

54-56. (Canceled)

57. (Currently Amended) A device manufacturing method comprising steps of:

~~exposing~~ transferring a pattern to a substrate using a scanning exposure apparatus as ~~recited~~ defined in claim 53; and

developing the ~~exposed~~ substrate to which the pattern has been transferred.

58. (Currently Amended) An apparatus according to claim 48, wherein ~~the~~ said plurality of electrostatic sensors are arranged at ~~each of~~ a plurality of positions in [[a]] the scanning direction ~~of the mask and the substrate~~.

59. (Currently Amended) An apparatus according to claim 53, wherein ~~the~~ said plurality of electrostatic sensors are arranged at ~~each of~~ a plurality of positions in [[a]] the scanning direction ~~of the mask and the substrate~~.

60. (New) An apparatus according to claim 37, wherein the layout information includes information of at least one of a dimension in the shot region, a position of the shot region in the substrate, and an arrangement of chip regions in the shot region.

61. (New) An apparatus according to claim 38, wherein the layout information includes information of at least one of a dimension of the shot region, a position of the shot region in the substrate, and an arrangement of chip regions in the shot region.

62. (New) An apparatus according to claim 48, wherein the layout information includes information of at least one of a dimension of the shot region, a position of the shot region in the substrate, and an arrangement of chip regions in the shot region.

63. (New) An apparatus according to claim 53, wherein the layout information includes information of at least one of a dimension of the shot region, a position of the shot region in the substrate, and an arrangement of chip regions in the shot region.